

EAST - [10632700.wsp.1]

File View Edit Tools Window Help

DBs: USPAT, EPO, JPO, DERWENT, IBM, TDB

Default operator: OR

Plurals: ☐ Highlight all hit terms initially: ☒

(multi-chip adj module\$1: multi adj chip adj module\$1 MCM, MCMs: multi-chip\$1 multi adj chip\$1) and (insulat\$3 and wire\$1 and (insulating near tape insulating near film))

373 term 64K bin Image Text HTML

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef
37	<input type="checkbox"/>	<input type="checkbox"/>	US 6541861 B2	20030401	13	Semiconductor device manufacturing method including forming step of SOI	257/751	257/347; 257/506;
38	<input type="checkbox"/>	<input type="checkbox"/>	US 6541077 B1	20030401	11	Silicon-containing polymer, process for its production, resist composition employing it,	427/503	427/515; 430/325;
39	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6534777 B2	20030318	34	Surface position detecting system and method having a sensor selection	250/559.29	250/559.4
40	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6534190 B1	20030318	27	Substrate material for mounting a semiconductor device, substrate for	428/472	257/E23.009; 428/216;
41	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6531773 B2	20030311	38	Semiconductor device	257/723	257/685; 257/737;
42	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6531706 B2	20030311	35	Surface position detecting system and method having an optimum value	250/559.29	250/205
43	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6531327 B2	20030311	22	Method for manufacturing semiconductor device utilizing semiconductor testing	438/17	438/14; 438/18
44	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6528879 B2	20030304	40	Semiconductor device and semiconductor module	257/729	257/738; 257/784;
45	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6524905 B2	20030225	20	Semiconductor device, and thin film capacitor	438/240	257/E21.008; 257/E23.144;
46	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6518163 B2	20030211	34	Method for forming bumps, semiconductor device, and solder paste	438/613	257/738; 257/E21.508;
47	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6515918 B2	20030204	41	Semiconductor device	365/189.09	365/226